LNJ952W8CRA1

Hight Bright Surface Mounting Chip LED

SV (Side View) -0.4 Type

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Power dissipation	P_{D}	80	mW
Forward current	I_{F}	20	mA
Pulse forward current *	I_{FP}	70	mA
Reverse voltage	V _R	5	V
Operating ambient temperature	T _{opr}	-30 to +85	°C
Storage temperature	T _{stg}	-40 to +100	°C

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

■ Lighting Color

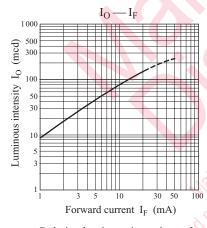
Blue

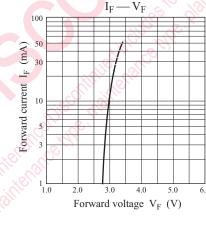
■ Electro-Optical Characteristics $T_a = 25$ °C±3°C

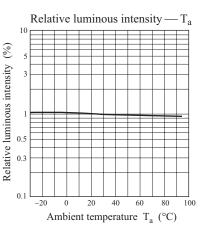
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity *1	I _O	$I_F = 10 \text{ mA}$	40.0	80.08	o Ville	mcd
Reverse current	I _R	$V_R = 5 V$		CYCIE	100	μΑ
Forward voltage	V _F	$I_F = 10 \text{ mA}$	2.7	3.0	3.7	V
Peak emission wavelength	$\lambda_{ m P}$	$I_F = 10 \text{ mA}$	9/1/00	455		nm
Dominant emission wavelength *2	λ_{d}	$I_F = 10 \text{ mA}$	452	460	468	nm
Spectral half band width	Δλ	$I_F = 10 \text{ mA}$	Jilli.	20		nm

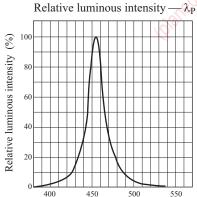
Note) *1: Measurement tolerance: ±20%

^{*2:} Measurement tolerance: ±3 nm

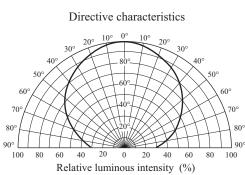


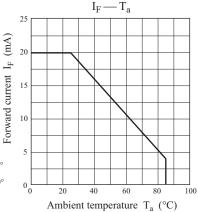






Peak emission wavelength λ_P (nm)

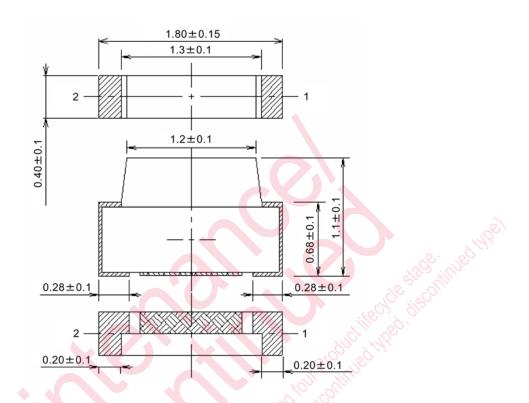




LNJ952W8CRA1 Panasonic

■ Package (Unit: mm)

KLTFSN2K5200



- Pin name
 - 1: Anode
 - 2: Cathode

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